

HONG KONG SCIENCE AND TECHNOLOGY PARKS CORPORATION

Request for Proposal (RFP) on

Provision of Programme Support, STEAM and Innovation Seminars and Workshops for Secondary Students

(Ref.: RFP/2024/CEOD/193)

The Hong Kong Science and Technology Parks Corporation (“HKSTP”) would like to invite interested parties (each a “Tenderer” and collectively, “Tenderers”) to submit proposals for the Provision of Programme Support, STEAM and Innovation Seminars and Workshops for Secondary Students during the tentative contract period from August 2024 to July 2025 (12 months).

Tenderers are invited to tender to provide the following services:

1. Central Coordinator and School Promotion and Recruitment
2. Content Planning and Speaker Invitation for Seminars & Workshops
3. Registration and Onsite Logistics Arrangements for Seminars and Workshops
4. Report and Evaluation of Seminars and Workshops
5. Design and Produce Learning Kit

Submission Deadline: 16 July 2024 at 12:00noon (Hong Kong Time)

Please refer to the updated Closing Date in HKSTP eTender system (click “Guest”)

Interested supplier shall register as HKSTP supplier successfully in eTender system to download the RFP/tender document.

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- Please enter HKSTP eTender system (<https://tender.hkstp.org/>) and click “Guest” to login for more details.*
 - For registering as HKSTP supplier, please refer to the “Supplier User Manual” for details. Company details including address, bank information, and business registration certificate are required for supplier registration. (Please download “Supplier User Manual” from “SUPPORT” page in HKSTP eTender system, <http://www.e-tendering.com/HKSTP/support.htm>)*
 - After completion of supplier registration, please download the tender documents from eTender system. Login eTender system as “Supplier” -> Click “Search” -> input the tender ref: “RFP/2024/CEOD/193” to search.*